MOS FIELD EFFECT TRANSISTOR **2SJ356**

P-CHANNEL MOS FET FOR HIGH-SPEED SWITCHING

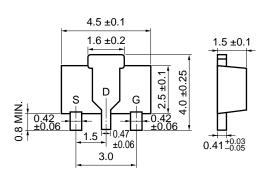
The 2SJ356 is a P-channel MOS FET of a vertical type and is a switching element that can be directly driven by the output of an IC operating at 5 V.

This product has a low ON resistance and superb switching characteristics and is ideal for driving the actuators and DC/DC converters.

FEATURES

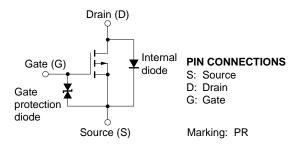
EC

- Can be directly driven by 5-V IC
- Low ON resistance
 R_{DS(on)} = 0.95 Ω MAX. @V_{GS} = -4 V, I_D = -1.0 A
 R_{DS(on)} = 0.50 Ω MAX. @V_{GS} = -10 V, I_D = -1.0 A



PACKAGE DIMENSIONS (in mm)

EQUIVALENT CIRCUIT



PARAMETER	SYMBOL	TEST CONDITIONS	RATING	UNIT
Drain to Source Voltage	Vdss	Vgs = 0	-60	V
Gate to Source Voltage	Vgss	V _{DS} = 0	-20/+10	V
Drain Current (DC)	ID(DC)		±2.0	А
Drain Current (Pulse)	D(pulse)	PW ≤ 10 ms Duty cycle ≤ 1 %	±4.0	A
Total Power Dissipation	Р⊤	16 $\text{cm}^2 \times 0.7$ mm, ceramic substrate used	2.0	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C

ABSOLUTE MAXIMUM RATINGS (T_A = 25 $^{\circ}$ C)

The internal diode connected between the gate and source of this product is to protect the product from static electricity. If the product is used in a circuit where the rated voltage of the product may be exceeded, connect a protection circuit.

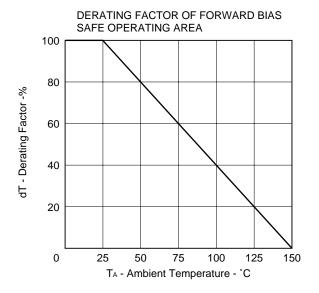
Take adequate preventive measures against static electricity when handling this product.

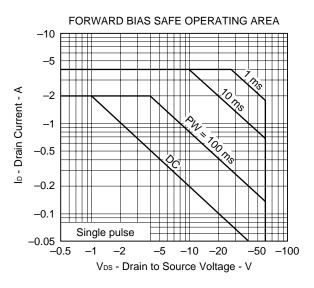
The information in this document is subject to change without notice.

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

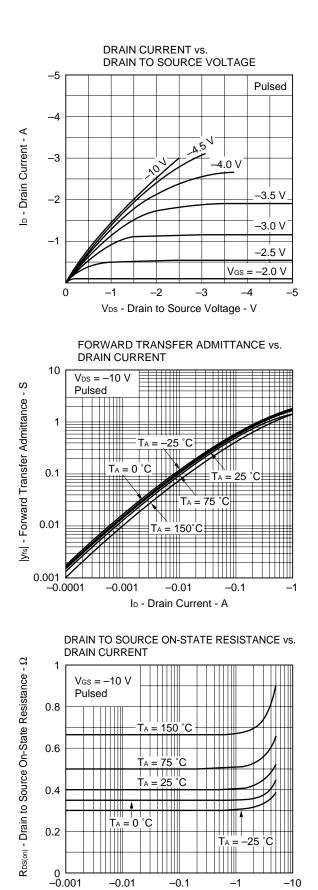
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Cut-Off Current	IDSS	$V_{DS} = -60 V, V_{GS} = 0$			-10	μΑ
Gate Leakage Current	lgss	$V_{GS} = -16/+10 V, V_{DS} = 0$			±10	μΑ
Gate Cut-Off Voltage	VGS(off)	$V_{DS} = -10 V, I_{D} = -1 mA$	-1.0	-1.4	-2.0	V
Forward Transfer Admittance	y _{fs}	$V_{DS} = -10 V$, $I_D = -1.0 A$	1.0			S
Drain to Source On-State Resistance	RDS(on)1	$V_{GS} = -4 V, I_D = -1.0 A$		0.65	0.95	Ω
Drain to Source On-State Resistance	RDS(on)2	$V_{GS} = -10 V$, $I_D = -1.0 A$		0.41	0.50	Ω
Input Capacitance	Ciss	V _{DS} = -10 V, V _{GS} = 0, f = 1.0 MHz		270		pF
Output Capacitance	Coss			145		pF
Reverse Transfer Capacitance	Crss			55		pF
Turn-On Delay Time	td(on)	$V_{DD} = -25 \text{ V}, \text{ Id} = -1.0 \text{ A}$ $V_{GS(on)} = -10 \text{ V}$ $R_G = 10 \Omega, \text{ RL} = 25 \Omega$		4.3		ns
Rise Time	tr			21		ns
Turn-Off Delay Time	td(off)			115		ns
Fall Time	tr			75		ns
Gate Input Charge	QG	$V_{DS} = -48 V,$ $V_{GS} = -10 V,$ $I_D = -2.0 A, I_G = -2 mA$		11.6		nC
Gate to Source Charge	QGS			1.0		nC
Gate to Drain Charge	Qgd			3.8		nC
Internal Diode Reverse Recovery Time	trr	I _F = 2.0 A, di/dt = 50 A/μs		82		ns
Internal Diode Reverse Recovery Charge	Qrr			94		nC

TYPICAL CHARACTERISTICS (T_A = 25 $^{\circ}$ C)

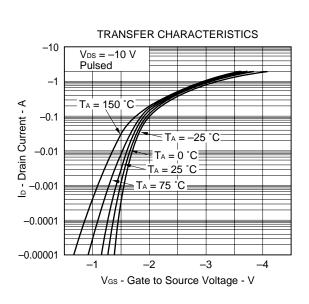




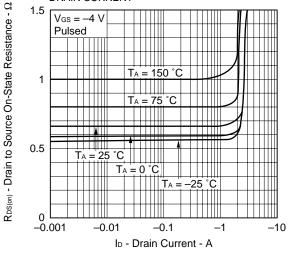




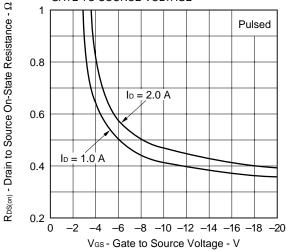
ID - Drain Current - A

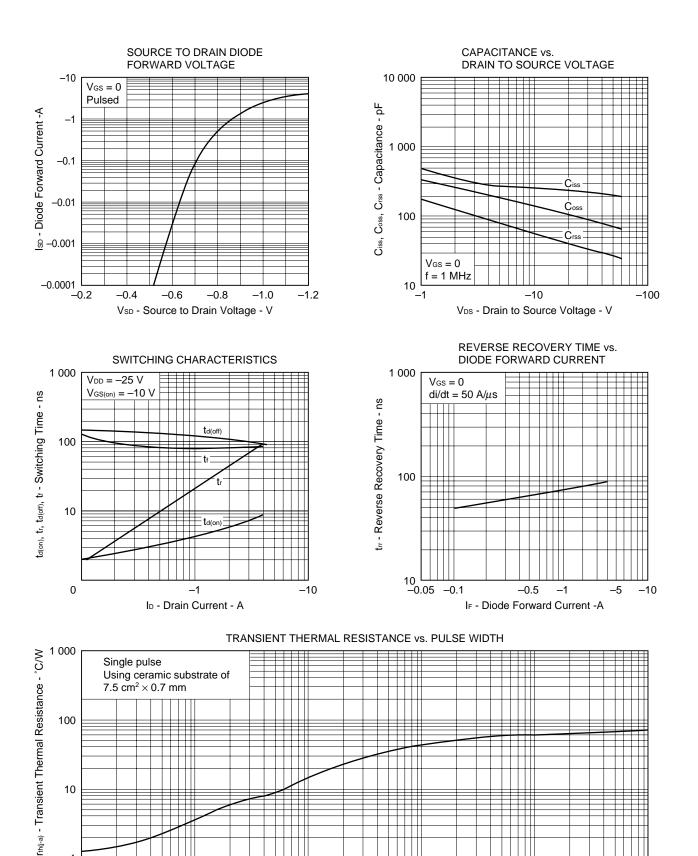


DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE





1 – 1 m

10 m

100 m

1

PW - Pulse Width - s

10

100

REFERENCE

Document Name	Document No.		
NEC semiconductor device reliability/quality control system	TEI-1202		
Quality grade on NEC semiconductor devices	IEI-1209		
Semiconductor device mounting technology manual	C10535E		
Guide to quality assurance for semiconductor devices	MEI-1202		
Semiconductor selection guide	X10679E		

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Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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Anti-radioactive design is not implemented in this product.

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